

1960.

Docket: TIJ-29448

Examiner: TBD

Art Unit: TBD

For: SEMICONDUCTOR PACKAGE INSULATION FILM AND MANUFACTURING
METHOD THEREOF

PRELIMINARY AMENDMENT

Assistant Commissioner For Patents
Washington, D. C. 20231

Sir:

"EXPRESS MAIL" mailing label number
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I hereby certify that the Preliminary Amendment and the accompanying Application is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 § CFR 1.10 on the above-mentioned date and is addressed to the Assistant Commissioner of Patents, Box New Applications, Washington, DC 20231.

Allen B. Kroger

Before examination of the above-identified patent application, please make the following amendments:

IN THE CLAIMS:

Please amend claims 1-11 as follows:

1. (Amended) An insulation film for providing an insulation substrate for carrying a semiconductor chip of a semiconductor package comprising: